

Package Height 3.5 mm max, 2.5~3.5 mm available Wave Soldering Temperature: 265°C max Highly stable and reliable crystal unit with a metallic package 3 Pin with ground pin

PARAMETERS	SPECIFICATION
Frequency Range	3.2~100MHz
Operation Mode	(3.2-40MHz) Fundamental (27-100MHz) 3rd/5rd Overtone
Loading Capacitance	20pF Std. 8pF~33pF available
Drive Level	10μW (300μW Max)
Frequency Tolerance	±10ppm±20ppm (at 25°C)
Equivalent Resistance	See Below
Frequency Stability	±2.5ppm±50ppm
Operating Temp. Range	0+50°C to -40+85°C
Storage Temp. Range	-55+125°C

FREQUENCY STABILITY VS. TEMPERATURE

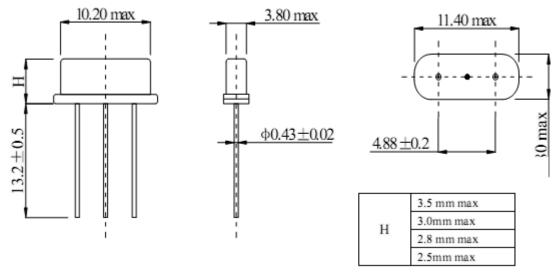
Operation Temperature	Frequency Stability					
Temperature Range	±2.5ppm	±5ppm	±10ppm	±20ppm	±30ppm	±50ppm
0+50°C	0	0	0	•	0	0

-10+60°C	0	0	•	0	0
-20+70°C		0	0	•	0
-40+85°C			0	0	•

• standart; o available

ESR (SERIES RESISTANCE RS)

Vibration Mode	ESR
AT CUT/FUND.	150Ω (MAX)
AT CUT/FUND.	120Ω (MAX)
AT CUT/FUND.	100Ω (MAX)
AT CUT/FUND.	80Ω (MAX)
AT CUT/FUND.	60Ω (MAX)
AT CUT/FUND.	50Ω (MAX)
AT CUT/FUND.	40Ω (MAX)
AT CUT/FUND.	30Ω (MAX)
AT 3rd /OT	100Ω (MAX)
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REFLOW SOLDERING PROFILE

